

Product Change Notice

Issue Date: 03-March-2023

Change Description:

Adding second source assembly (Signetics Korea) for BCM43566, BCM43569

Parts Affected:

BCM43566PKFFBG0
BCM43566PKFFBG
BCM43569PKFFBG

Description and Extent of Change:

Add Signetics Korea as an assembly supplier for the above devices. This supplements, and does not replace, supply from the first source (Amkor China).

Reasons for Change:

Supply Chain manufacturing flexibility and capacity

Effect of Change on Fit, Form, Function, Quality, or Reliability:

There will be no change to fit, form, function, quality or reliability. The device specification will remain the same, which will ensure product electrical performance remains the same. Appropriate electrical characterization and reliability qualification has been performed on representative products to ensure normal parametric distribution, consistent electrical performance, and reliability.

Effective Date of Change:

June 3, 2023

Software / Firmware Update:

As with all changes please check with your Broadcom FAE to determine if any software or firmware updates are required as a result of this change.

Qualification Data (BCM43566):

TYPE OF PRODUCT	Broadband and Connectivity
PRODUCT	BCM43566xKFFBGx
PROCESS TECHNOLOGY	40nm
PACKAGE TYPE	RFCFBGA, 10x10, 242 pins
FOUNDRIY SOURCE	TSMC, UMC
ASSEMBLY SOURCE	ASE / AMKOR / SIGNETICS

TEST	SPEC	Conditions	Sample Size	Read point (hrs/cycles ~)	Results
ESD – HBM	JS-001-2012	$\geq \pm 1500V$	3	N/A	Pass
ESD – CDM	JESD22-C101	$\geq \pm 300V$	3	N/A	Pass
LU	JESD-STD-78	$\geq \pm 200mA$	3	N/A	Pass
EFR	JESD22-A108	125°C, >80% Node, Vcc= Max	154	24 Hrs	Pass
HTOL	JESD22-A108	125°C, >80% Node, Vcc=Max	77	192 Hrs	Pass
				500 Hrs	Pass
				1000 Hrs	Pass
uHAST	JESD22-A118	130°C, 85% RH, No bias (pre-con parts)	77	96 Hrs	Pass
TC	JESD22-A104	-55°C to 125°C air to air (pre-con parts)	77	500 cycles	Pass
				700 cycles	Pass
				1000 cycles	Pass
HTSL	JESD22-A103	Ta= 150°C.	77	500 Hrs	Pass
				1000 Hrs	Pass
MSL	JESD-A113	Level 3(30°C, 60%RH)	154	96 Hrs	Pass

Please contact your Broadcom field sales engineer or Contact Center for any questions or support requirements. Please acknowledge the receipt of the notice within 30 days of delivery. Lack of acknowledgement within 30 days constitutes acceptance of the change per JEDEC J-STD-046.

**Qualification Data (BCM43569):**

PRODUCT	BCM43569xKFFBG
PROCESS TECHNOLOGY	40nm
PACKAGE TYPE	FCFBGA, 10x10, 254 balls
FOUNDRY SOURCE	UMC
ASSEMBLY SOURCE	SIGNETICS / SPIL / AMKOR

TEST	SPEC	Conditions	Sample Size	Read point (hrs/cycles ~)	Results
ESD – HBM	JS-001-2012	$\geq \pm 1500V$	3	N/A	Pass
ESD – CDM	JESD22-C101	$\geq \pm 300V$	3	N/A	Pass
LU	JESD-STD-78	$\geq \pm 200mA$	3	N/A	Pass
EFR	JESD22-A108	125°C, >80% Node, Vcc= Max	154	24 Hrs	Pass
HTOL	JESD22-A108	125°C, >80% Node, Vcc=Max	77	192 Hrs	Pass
				500 Hrs	Pass
				1000 Hrs	Pass
uHAST	JESD22-A118	130°C, 85% RH, No bias (pre-con parts)	77	96 Hrs	Pass
TC	JESD22-A104	-55°C to 125°C air to air (pre-con parts)	77	500 cycles	Pass
				700 cycles	Pass
				1000 cycles	Pass
HTSL	JESD22-A103	Ta= 150°C.	77	500 Hrs	Pass
				1000 Hrs	Pass
MSL	JESD-A113	Level 3(30°C, 60%RH)	154	96 Hrs	Pass

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